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FOR IMMEDIATE RELEASE

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Alpha and Omega Semiconductor Expands Surface Mount Package offering with new LFPAK 5x6 Package for High Performance and High-Reliability Requirements

New AOS LFPAK 5x6 package provides the ruggedness needed for high-current applications in industrial, server power, solar, and telecommunication applications

SUNNYVALE, Calif., Aug. 21, 2024 – Alpha and Omega Semiconductor Limited (AOS) (Nasdaq: AOSL), a designer, developer, and global supplier of a broad range of discrete power devices, wide band gap power devices, power management ICs, and modules, today announced its new highly robust power MOSFET LFPAK 5x6 package. AOS's new LFPAK product offering is available in a wide range of voltages: 40V, 60V, and 100V, and it is designed to withstand harsh environments while maintaining MOSFET performance. The new devices are found in a broad range of applications such as industrial, server power, telecommunications, and solar, where high reliability is required.

AOS's LFPAK packaging enables higher board-level reliability due to key packaging features such as gull-wing leads, which offer a ruggedized solution for board-level environmental stresses. The gull-wing leads also enable optical inspection during PCB manufacturing. Another feature enhancement is the LFPAK's larger copper clip, which improves electrical and thermal performance. Advantages of the large clip include improved current handling capabilities, reduced on-resistance, and better heat dispersion compared to wire bonding. A large clip also has low parasitic inductance, enabling lower spike voltage in switching applications. All these features significantly improve the robustness of the MOSFET, and utilizing AOS's advanced shielded gate MOSFET Technology (AlphaSGT™) enables designers to find an optimized solution to achieve high reliability under the harshest environmental conditions.

"Designers have long trusted AOS power semiconductors in their applications, and LFPAK 5x6 will expand solution capability," said Peter H. Wilson, Marketing Sr. Director of the MOSFET product line at AOS.

Technical Highlights

Part Number	VDS (V)	VGS (±V)	ID @ 25°C (A)	RDS(ON) max (mΩ) at VGS=10V	Tj max (°C)
AOLF66412	40	20	352	1.5	175
AOLF66413	40	20	374	1.5	175
AOLF66417	40	20	200	2.6	175

AOLF66610	60	20	294	2	175
AOLF66910	100	20	187	4.7	175

Pricing and Availability

The LFPAK 5x6 family is immediately available in production quantities with a lead time of 14-16 weeks. The unit price for 1,000 pieces for AOLF66412, AOLF66413, AOLF66417, AOLF66610, and AOLF66910 are respectively $1.15, $1.17, $0.78, $1.65, and $2.1.

About AOS

Alpha and Omega Semiconductor Limited, or AOS, is a designer, developer, and global supplier of a broad range of discrete power devices, wide band gap power devices, power management ICs, and modules, including a wide portfolio of Power MOSFET, SiC, IGBT, IPM, TVS, HV Gate Drivers, Power IC, and Digital Power products. AOS has developed extensive intellectual property and technical knowledge that encompasses the latest advancements in the power semiconductor industry, which enables us to introduce innovative products to address the increasingly complex power requirements of advanced electronics. AOS differentiates itself by integrating its Discrete and IC semiconductor process technology, product design, and advanced packaging know-how to develop high-performance power management solutions. AOS' portfolio of products targets high-volume applications, including portable computers, flat-panel TVs, LED lighting, smartphones, battery packs, consumer and industrial motor controls, automotive electronics, and power supplies for TVs, computers, servers, and telecommunications equipment. For more information, please visit www.aosmd.com.

Forward-Looking Statements

This press release contains forward-looking statements that are based on current expectations, estimates, forecasts, and projections of future performance based on management's judgment, beliefs, current trends, and anticipated product performance. These forward-looking statements include, without limitation, references to the efficiency and capability of new products and the potential to expand into new markets. Forward-looking statements involve risks and uncertainties that may cause actual results to differ materially from those contained in the forward-looking statements. These factors include but are not limited to, the actual product performance in volume production, the quality and reliability of the product, our ability to achieve design wins, the general business and economic conditions, the state of the semiconductor industry, and other risks as described in the Company's annual report and other filings with the U.S. Securities and Exchange Commission. Although the Company believes that the expectations reflected in the forward-looking statements are reasonable, it cannot guarantee future results, level of activity, performance, or achievements. You should not place undue reliance on these forward-looking statements. All information provided in this press release is as of today's date unless otherwise stated, and AOS undertakes no duty to update such information except as required under applicable law.

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